

### 6593182 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB	1		6593182	Any	Printed Circuit Board	
C1, C2, C7, C8, C19, C20, C25, C26	8	0.01uF	LLL185R71E103MA01L	MuRata	CAP, CERM, 0.01uF, 25V, +/-20%, X7R, 0306	0306
C3, C4, C5, C6, C21, C22, C23, C24	8	2200pF	LLL185R71H222MA01L	MuRata	CAP, CERM, 2200pF, 50V, +/-20%, X7R, 0306	0306
C9, C27	2	0.01uF	GRM188R71C103KA01D	MuRata	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603	0603
C10, C13, C14, C28, C32, C34	6	10uF	TPSA106K010R0900	AVX	CAP, TA, 10uF, 10V, +/-10%, 0.9 ohm, SMD	3216-18
C11, C29	2	0.1uF	C1005X5R1A104K	TDK	CAP, CERM, 0.1uF, 10V, +/-10%, X5R, 0402	0402
C12, C17, C18, C30	4	0.01uF	C1005X7R1E103K	TDK	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402
GND1, GND2, TPG1, TPG2	4	Black	5011	Keystone Electronics	Test Point, TH, Multipurpose, Black	
IN+, IN-, OUT+, OUT-, PD1, PD2, Vcm1, Vcm2	8		142-0701-851	Emerson Network Power	Connector, SMT, End launch SMA 50 ohm	SMA End Launch
Jpd1, Jpd2, JV+, JV-	4		TSW-102-07-G-S	Samtec, Inc.	Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	TSW-102-07-G-S
L1, L2	2	330 ohm	BLM18SG331TN1D	MuRata	Ferrite Bead, 330 ohm @ 100 MHz, 1.5 A, 0603	0603
R1, Ri1+	2	137	CRCW0402137RFKED	Vishay-Dale	RES, 137, 1%, 0.063 W, 0402	0402
R2, Ri1-	2	36.5	CRCW040236R5FKED	Vishay-Dale	RES, 36.5, 1%, 0.063 W, 0402	0402
Rcm1+, Rcm1-, Rcm2+, Rcm2-	4	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00k ohm, 1%, 0.1W, 0603	0603
Rf1+, Rf1-, Rf2+, Rf2-	4	174	CRCW0402174RFKED	Vishay-Dale	RES, 174, 1%, 0.063 W, 0402	0402
Ro1+, Ro1-, Ro2+, Ro2-	4	40.2	CRCW040240R2FKED	Vishay-Dale	RES, 40.2 ohm, 1%, 0.063W, 0402	0402
Rsd1, Rsd2	2	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9 ohm, 1%, 0.1W, 0603	0603
SH-Jpd1_2-OPEN, SH-Jpd2_2-OPEN, SH-JV+_1-2, SH-JV-_1-2	4	1x2	382811-6	AMP	Shunt, 100mil, Gold plated, Black	
U1, U2	2		LMH5401IRMSR	Texas Instruments	8GHz Ultra Wideband Fully Differential Amplifier, RMS0014A	RMS0014A
V1+, V2+	2	Red	5010	Keystone Electronics	Test Point, TH, Multipurpose, Red	
V1-, V2-	2	Yellow	5014	Keystone	Test Point, Multipurpose, Yellow, TH	Yellow Multipurpose Testpoint
C15, C16, C31, C33	0		Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603
R3, R4, R5, R6, R8, R9, R10, R11	0		Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	0402
RB1+, RB1-, RB2+, RB2-, Rtcm1, Rtcm2	0		Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	0603

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